REMARKS

The present invention teaches, among other things, a carrier having a die bonding area and a power pad and a ground pad disposed outside the die bonding area; a die having a plurality of die pads on an active surface and attaching to the die bonding area from a back surface; at least a passive component disposed between the power pad and the ground pad and having at least two electrodes connected to the power pad and the ground pad, respectively; at least a conducting wire having one end connected to one of the plurality of the die pads and the other end connected to one of the electrodes.

The APA teaches, on the other hand, a conducting wire having one end connected to the die pad and the other connected to the power pad or the ground pad. As a result, the length of the conducting wire is longer. Although Liu teaches a method for reducing the wire sweep problem, the configuration of the wiring and the ultimate result are different from the invention. First of all, Liu teaches using two wires 160, 170 to connect from the die pad 110a to the power ring 106 or the ground ring 104. Liu teaches using the wire 160 to connect from the die pad 110a to a bonding section 150 of the capacitor and the wire 170 to connect from the bonding section 150 to the power ring 106. Therefore, the length of the conducting wire is definitely not shorter as taught in the invention. Moreover, Liu does not teach or suggest connecting the conducting wire 160 form the die pad to the electrode (contact 120a or b) of the passive component (capacitor 120). Accordingly, Liu reference does not show the kind of wire structure that would be useful if implemented in the AAPA. If Liu reference were to be combined with the AAPA, the combination would teach using two wires to connect a die pad to the power ring, wherein a first

wire 160 connects a die pad to a bonding section of the passive component and a second wire 170 connects the bonding section of the passive component to the power ring, rather than a single wire having one end connecting the die pad and another end connecting the electrode.

Accordingly, Applicants respectfully submit that the prior art references, neither alone nor in combination teach nor suggest the claimed invention. Accordingly, the allowance of claims 1 to 19 is earnestly requested. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,
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